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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











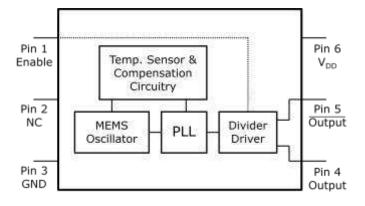
Low-Jitter Precision HCSL Oscillator

General Description

The DSC1104 & DSC1124 series of high performance oscillators utilizes a proven silicon MEMS technology to provide excellent jitter and stability over a wide range of supply voltages and temperatures. eliminating the need for quartz or SAW MEMS oscillators significantly technology, enhance reliability and accelerate product development, while meeting stringent clock criteria performance for a variety communications, storage, and networking applications.

DSC1104 has a standby feature allowing it to completely power-down when EN pin is pulled low; whereas for DSC1124, only the outputs are disabled when EN is low. Both oscillators are available in industry standard packages, including the small 3.2x2.5 mm², and are "drop-in" replacements for standard 6-pin HCSL quartz crystal oscillators.

Block Diagram



Output Enable Modes

EN Pin	DSC1104	DSC1124
High	Outputs Active	Outputs Active
NC	Outputs Active	Outputs Active
Low	Standby	Outputs Disabled

Features

- Low RMS Phase Jitter: <1 ps (typ)
- High Stability: ±10, ±25, ±50 ppm
- Wide Temperature Range
 - o Industrial: -40° to 85° C
 - o Ext. commercial: -20° to 70° C
- High Supply Noise Rejection: -50 dBc
- Short Lead Time: 2 Weeks
- Wide Freq. Range: 2.3 to 460 MHz
- Small Industry Standard Footprints
 2.5x2.0, 3.2x2.5, 5.0x3.2, & 7.0x5.0 mm
- Excellent Shock & Vibration Immunity
 - Qualified to MIL-STD-883
- High Reliability
 - o 20x better MTF than quartz oscillators
- Low Current Consumption
- Supply Range of 2.25 to 3.6 V
- Standby & Output Enable Function
- Lead Free & RoHS Compliant
- LVPECL & LVDS Versions Available

Applications

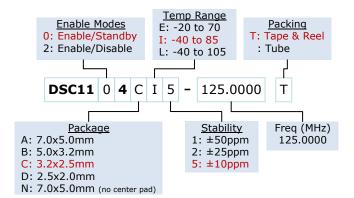
- Storage Area Networks
 - o SATA, SAS, Fibre Channel
- Passive Optical Networks
 - o EPON, 10G-EPON, GPON, 10G-PON
- Ethernet
 - 1G, 10GBASE-T/KR/LR/SR, and FCoE
- HD/SD/SDI Video & Surveillance
- PCI Express: Gen 1 & Gen 2
- DisplayPort



Absolute Maximum Ratings

Item	Min	Max	Unit	Condition
Supply Voltage	-0.3	+4.0	V	
Input Voltage	-0.3	$V_{DD} + 0.3$	V	
Junction Temp	-	+150	°C	
Storage Temp	-55	+150	°C	
Soldering Temp	-	+260	°C	40sec max.
ESD	-		V	
HBM		4000		
MM		400		
CDM		1500		

Ordering Code



Note: 1000+ years of data retention on internal memory

Specifications

Parameter		Condition	Min.	Тур.	Max.	Unit
Supply Voltage ¹	V_{DD}		2.25		3.6	V
Supply Current	I_{DD}	EN pin low – outputs are disabled DSC1104 DSC1124		20	0.095 22	mA
Frequency Stability	Δf	Includes frequency variations due to initial tolerance, temp. and power supply voltage			±10 ±25 ±50	ppm
Aging	Δf	1 year @25°C			±5	ppm
Startup Time ²	t _{su}	T=25°C			5	ms
Input Logic Levels Input logic high Input logic low	$egin{array}{c} egin{array}{c} \egin{array}{c} \egin{array}{c} \egin{array}{c} \egin{array}{c} \egin{array}{c} \egin{array}$		0.75xV _{DD}		- 0.25xV _{DD}	V
Output Disable Time ³	t_DA				5	ns
Output Enable Time	t _{EN}	DSC1104 DSC1124			5 20	ms ns
Enable Pull-Up Resistor ⁴		Pull-up resistor exist		40		kΩ
		HCSL Outputs				
Supply Current	I_{DD}	Output Enabled, R_L =50 Ω		40	42	mA
Output Logic Levels Output logic high Output logic low	V _{OH} V _{OL}	$R_L=50\Omega$	0.725 -		- 0.1	V
Pk to Pk Output Swing		Single-Ended		750		mV
Output Transition time ³ Rise Time Fall Time	t _R t _F	20% to 80% $R_L = 50\Omega$, $C_L = 2pF$	200		400	ps
Frequency	f_0	Single Frequency	2.3		460	MHz
Output Duty Cycle	SYM	Differential	48		52	%
Period Jitter	J_{PER}			2.5		ps _{RMS}
Integrated Phase Noise	$J_{ ext{PH}}$	200kHz to 20MHz @156.25MHz 100kHz to 20MHz @156.25MHz 12kHz to 20MHz @156.25MHz		0.25 0.37 1.7	2	ps _{RMS}

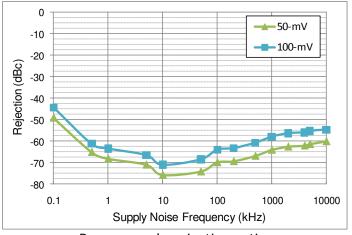
Notes:

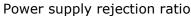
- 1.
- Pin 6 V_{DD} should be filtered with 0.1uf capacitor. t_{su} is time to 100ppm of output frequency after V_{DD} is applied and outputs are enabled. Output Waveform and Test Circuit figures below define the parameters. 2.

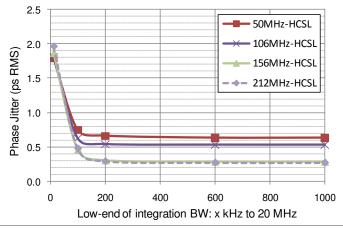
Output is enabled if pad is floated or not connected.



Nominal Performance Parameters (Unless specified otherwise: T=25° C, V_{DD}=3.3 V)

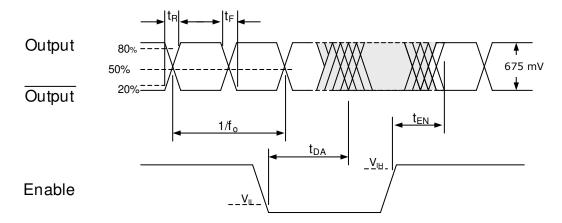




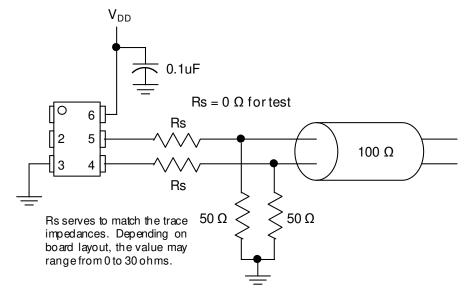


Phase jitter (integrated phase noise)

Output Waveform

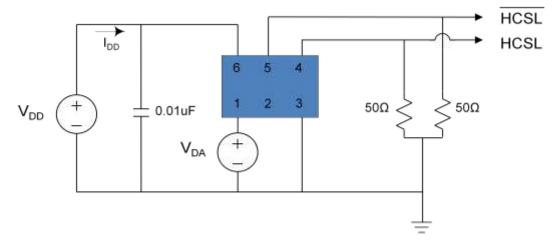


Typical Termination Scheme

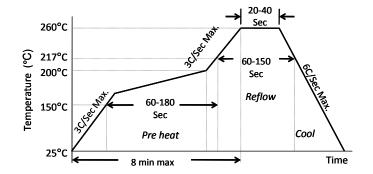




Test Circuit



Solder Reflow Profile

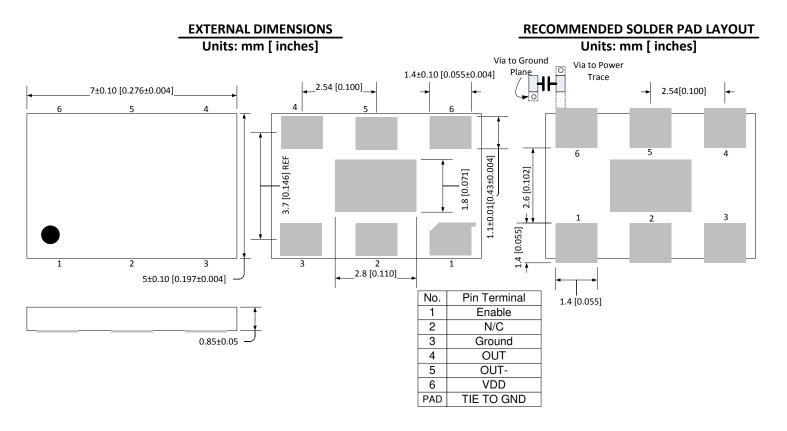


MSL 1 @ 260°C refer to JSTD-020C		
Ramp-Up Rate (200°C to Peak Temp)	3°C/Sec Max.	
Preheat Time 150°C to 200°C	60-180 Sec	
Time maintained above 217°C	60-150 Sec	
Peak Temperature	255-260°C	
Time within 5°C of actual Peak	20-40 Sec	
Ramp-Down Rate	6°C/Sec Max.	
Time 25°C to Peak Temperature	8 min Max.	

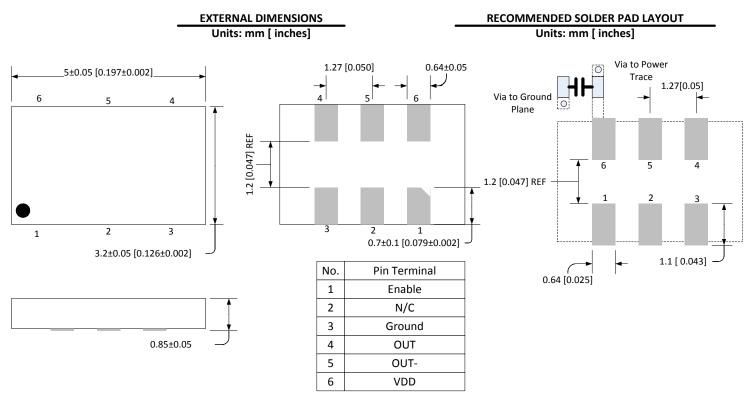


Package Dimensions

7.0 x 5.0 mm Plastic Package



5.0 x 3.2 mm Plastic Package

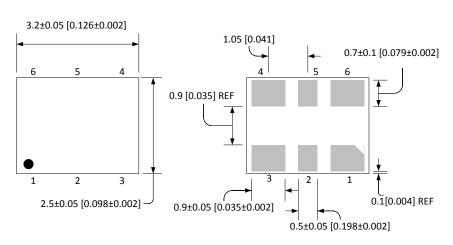


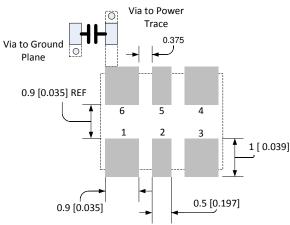


3.2 x 2.5 mm Plastic Package

Units: mm [inches]

RECOMMENDED SOLDER PAD LAYOUT Units: mm [inches]







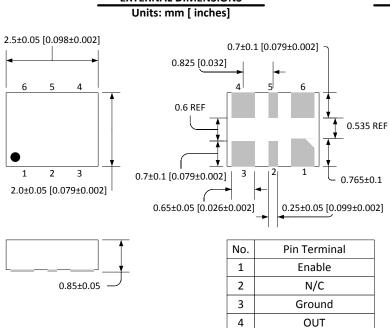
No.	Pin Terminal
1	Enable
2	N/C
3	Ground
4	OUT
5	OUT-
6	VDD

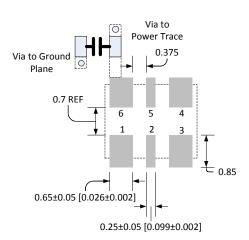
2.5 x 2.0 mm Plastic Package



RECOMMENDED SOLDER PAD LAYOUT

Units: mm [inches]





OUT-

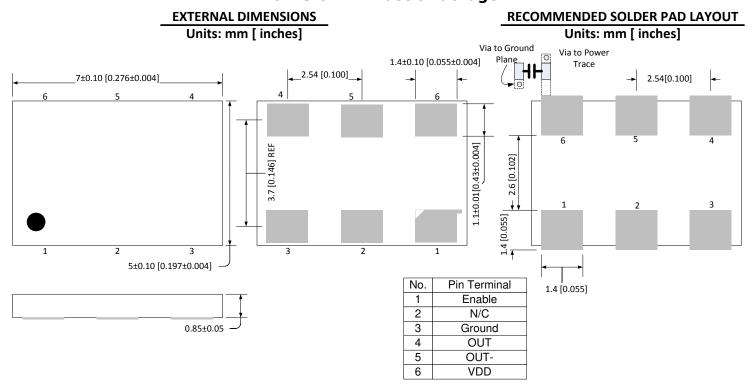
VDD

5

6



7.0 x 5.0 mm Plastic Package



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MICREL, Inc. • 2180 Fortune Drive, San Jose, California 95131 • USA

Phone: +1 (408) 944-0800 • Fax: +1 (408) 474-1000 • Email: hbwhelp@micrel.com • <u>www.micrel.com</u>